



100% Material Declaration Data Sheet PCG44

PK116 (v1.3) July 29, 2011

Average Weight: 2.3596g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die (FPGA)					0.007637	0.32
	Silicon	7440-21-3	100.00	Silicon IC	0.007637	
Die attach material					0.001992	0.08
	Resin	Trade Secret	25.00		0.000498	
	Silver (Ag)	7440-22-4	75.00		0.001494	
Mold Compound					1.825990	77.38
	Resin	Trade Secret	7.50		0.136949	
	Silica	60676-86-0	86.00	Filler	1.570351	
	Carbon Black	1333-86-4	0.50	Polymer	0.009130	
	Epoxy Cresol Novolac	Trade Secret	2.00	Hardener	0.036520	
	Phenolic Resin	Trade Secret	4.00	Colouring	0.073040	
Lead Frame					0.498490	21.13
	Copper (Cu)	7440-50-8	99.90	Base metal	0.497992	
	Zirconium (Zr)	7440-67-7	0.10	Base metal	0.000498	
Lead Frame Plating					0.001490	0.06
	Silver (Ag)	7440-22-4	100.00	Base metal	0.001490	
Gold Wire					0.001818	0.08
	Gold	7440-57-5	100.00	Metallurgy	0.001818	
External Plating					0.022210	0.94
	Tin (Sn)	7440-31-5	100.00	Base metal	0.022210	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/21/06	1.0	Initial Release
6/08/06	1.1	100% Material Declaration
9/28/06	1.2	Updated component descriptions
7/29/11	1.3	Update resin component weight

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